

# **Final Product Change Notification**

Issue Date: 16-Feb-2020 Effective Date: 16-May-2020

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online

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## **Management Summary**

Transition from leadless HVSON package product UJA116x to successor CAN FD drop-in replacement product UJA116xA (x=1, 2, 3, 4, 7 and 8)

## **Change Category**

[] Wafer Fab Process	[] Assembly	[] Product Marking	[] Test Location	[X] Design
	Process			
[] Wafer Fab Materials	[X]	[] Mechanical	[]Test	[] Errata
	Assembly	Specification	Process	
	Materials	•		
[] Wafer Fab Location	[]	[X]	[]Test	[X] Electrical
	Assembly	Packing/Shipping/Labeli	ng Equipment	spec./Test
	Location			coverage
[] Firmware	[] Other			3

Transition from Leadless HVSON Package Product UJA116x to Successor CAN FD Drop-in Replacement Product UJA116xA

## **Description of Change**

NXP Product Line In Vehicle Networking (PL IVN) recently informed you via Customer Information Notification (CIN) 201909013I of three design-related issues affecting products UJA116x (x=1, 2, 3, 4, 7 or 8). These could potentially affect your application using products UJA116x, and may cause failures or customer returns.

In October 2019 NXP PL IVN released the successor products UJA116xA, fulfilling additional CAN FD specifications as required by certain OEMs (5 Mbit/s timing, short Wake Up Pattern (WUP) wake-up time and improved EMC immunity). In these UJA116xA products before-mentioned three issues have been fixed through minor design changes.

This Product Change Notification (PCN) announces the transition from UJA116x to these drop-in replacements UJA116xA. Apart from the design changes needed to fulfill the additional CAN FD requirements and fix the before-mentioned issues, there is an industrial standardization to a copper (Cu) bondwire and associated mold compound change. For the new UJA116xA products the following holds:

- Form: Only change is Cu wire, and associated change of mold compound
- Fit: No change, UJA116xA is a drop-in replacement for UJA116x
- Function: Improved through fulfillment of additional datasheet CAN FD specifications
- Performance: Improved EMC immunity
- Reliability: No change, products UJA116xA are fully AEC-Q100 qualified and released
- Quality: Improved through minor design changes to fix before-mentioned three issues

Three months after this PCN, in May 2020, a separate formal Discontinuation Notification (DN) for the 'old' UJA116x products will be sent, with a 1-year Last Time Buy (LTB) period, followed by a 1-year Last Time Shipment (LTS) period. This implies that you are required to act on this PCN, as you can no longer order the current UJA116x products after this period.

Attached to this PCN are documents that enable you to assess the change (qualification):

- A document with details on the change:
- ---- Between UJA116x and UJA116xA datasheets
- ----- A migration guide, describing the drop-in replacement of UJA116x with UJA116xA in your application
- A full AEC-Q100 qualification report for products UJA116xA
- The UJA116xA datasheets (x=1, 2, 3, 4, 7 or 8)
- The ZVEI Delta Qualification Matrix (DeQuMa) for this change

PPAPs and samples of products UJA116xA (x=1, 2, 3, 4, 7 or 8) are available on request. This information should enable you to transition to the new UJA116xA products with a minor, if any, delta qualification.

## **Reason for Change**

The successor products UJA116xA, fulfilling additional CAN FD specifications as required by certain OEMs, were already planned. These successor products UJA116xA also contain minor design fixes for three issues that could potentially affect your application and may cause failures or customer returns.

The transition from the current products UJA116x to the successor products UJA116xA, as announced by this Product Change Notification (PCN), is necessary to eliminate the risk for these failures or customer returns and meet the OEM-required additional CAN FD specifications.

#### **Identification of Affected Products**

Top side marking

In the attachment to this PCN it is shown how the product names and the marking changes.

## **Product Availability**

## **Sample Information**

Samples are available upon request

## Production

Planned first shipment 17-May-2020

## Anticipated Impact on Form, Fit, Function, Reliability or Quality

See above under the heading 'Description of Change'.

#### **Data Sheet Revision**

A new datasheet will be issued

## **Disposition of Old Products**

Existing inventory will be shipped until depleted

#### **Related Notifications**

## NotificationIssue Date Effective DateTitle

201909013I 06-Dec- 04-Jan-2020 Important Information on Products UJA116x, UJA113x and TJA1145

## **Timing and Logistics**

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 17-Mar-2020.

#### Remarks

Please use the link 'view online' under the heading 'Additional information' above, to log in to the NXP e-PCN system you're subscribed to, in order to obtain the attached documents with relevant detailed information from the tab 'Files':

- An attachment with more detailed description of the change
- An AEC-Q100 reliability results report
- The UJA116xA datasheets (x=1, 2, 3, 4, 7 or 8)
- A ZVEI Delta Qualification Matrix (DeQuMa) for the change, both in pdf and zipped excel format

Should you not be able to obtain these documents, please contact your NXP sales representative or the e-mail address mentioned below under 'Contact and Support'.

## **Contact and Support**

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

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**NXP Semiconductors** 

High Tech Campus, 5656 AG Eindhoven, The Netherlands

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#### **Affected Part Numbers**

UJA1162TK,118 UJA1167TK/VX,118 UJA1163TK,118 UJA1164TK,118